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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: IWASAKI, et al

Serial No.: 09/985,904

Filed: November 6, 2001

For: SEMICONDUCTOR DEVICE HAVING LAYERED
INTERCONNECT STRUCTURE WITH A COPPER OR PLATINUM
CONDUCTING FILM AND A NEIGHBORING FILM (As Amended)

Group Art Unit: 2813

Examiner: Stephen W. Smoot

**SUPPLEMENTING SUBMISSION UNDER 37 CFR § 1.114
(AMENDMENT)**

Mail Stop
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

June 11, 2003

Sir:

Please further amend the above-identified application, prior to further
examination thereof, and as a Supplementing Submission for the concurrently filed
Request for Continued Examination (RCE) Transmittal, as follows:

IN THE CLAIMS:

Please add the following new claims to the application:

--15. A semiconductor device having a layered interconnection structure

E according to claim 14, wherein said insulating film is a silicon oxide film.

16. A semiconductor device having a layered interconnection structure

according to claim 13, wherein said insulating film is a silicon oxide film.--

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